

Description

The AOD4130-HXY uses advanced trench technology

to provide excellent $R_{\text{DS}(\text{ON})},$ low gate charge and

operation with gate voltages as low as 4.5V. This

device is suitable for use as a

Battery protection or in other Switching application.

General Features

 $V_{DS} = 60V I_D = 30 A$

 $R_{DS(ON)}$ < 26m Ω @ V_{GS}=10V

Application

Battery protection

Load switch

Uninterruptible power supply

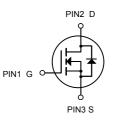
Package Marking and Ordering Information

Due du et ID	Deals	Marking Ofu (DOO)		
Product ID	Pack	Marking	Qty(PCS)	
AOD4130-HXY	TO252-2L	30N06XXXX YYYY	2500	

Absolute Maximum Ratings (Tc=25°Cunless otherwise noted)

Symbol	Parameter	Rating	Units
VDS	Drain-Source Voltage	60	V
Vgs	Gate-Source Voltage	±20	V
I⊳@Tc=25°C	Continuous Drain Current, V _{GS} @ 10V ¹	30	А
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ 10V ¹	15	А
I _D @T _A =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	5.6	А
I _D @T _A =70°C	Continuous Drain Current, V _{GS} @ 10V ¹	4.5	А
Ідм	Pulsed Drain Current ²	46	А
EAS	Single Pulse Avalanche Energy ³	25.5	mJ
las	Avalanche Current	22.6	А
P _D @T _C =25°C	Total Power Dissipation ⁴	34.7	W
P _D @T _A =25°C	Total Power Dissipation ⁴	2	W
Тѕтс	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 150	°C





N-Channel MOSFET



AOD4130-HXY

N-Channel Enhancement Mode MOSFET

Reja	Thermal Resistance Ju	Thermal Resistance Junction-Ambient ¹		62		°C/W	
Rejc Thermal Resistan		Junction-Case ¹	3.6		°C/W		
ectrical C	Characteristics (TJ=25 °C, unle	ss otherwise noted)					
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
BVDSS	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	60			V	
∆BV _{DSS} /∆TJ	BV _{DSS} Temperature Coefficient	Reference to 25°C,I _D =1mA		0.063		V/°C	
		V _{GS} =10V , I _D =15A		22	26		
RDS(ON)	Static Drain-Source On-Resistance ²	V _{GS} =4.5V , I _D =10A		30	38	mΩ	
VGS(th)	Gate Threshold Voltage		1.2		2.5	V	
$\bigtriangleup V_{\text{GS(th)}}$	V _{GS(th)} Temperature Coefficient	—V _{GS} =V _{DS} , I _D =250uA		-5.24		mV/°	
		V _{DS} =48V , V _{GS} =0V , T _J =25°C			1		
IDSS	Drain-Source Leakage Current	V _{DS} =48V , V _{GS} =0V , T _J =55°C			5	uA	
lgss	Gate-Source Leakage Current	V_{GS} =±20V , V_{DS} =0V			±100	nA	
gfs	Forward Transconductance	V _{DS} =5V , I _D =15A		17		S	
R _g	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		3.2		Ω	
Qg	Total Gate Charge (4.5V)			12.6		nC	
Q _{gs}	Gate-Source Charge	V _{DS} =48V , V _{GS} =4.5V , I _D =12A		3.2			
Q_{gd}	Gate-Drain Charge	_		6.3			
Td(on)	Turn-On Delay Time			8			
Tr	Rise Time	V _{DD} =30V , V _{GS} =10V ,		14.2		ns	
Td(off)	Turn-Off Delay Time	—R _G =3.3 , I _D =10A		24.4			
T _f	Fall Time			4.6			
Ciss	Input Capacitance			1378			
Coss	Output Capacitance			86		pF	
Crss	Reverse Transfer Capacitance			64			
ls	Continuous Source Current ^{1,5}				23	A	
lsм	Pulsed Source Current ^{2,5}	$-V_G=V_D=0V$, Force Current			46	A	
Vsd	Diode Forward Voltage ²				1.2	V	

Note :

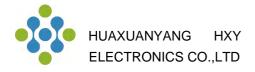
1. The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper.

2.The data tested by pulsed , pulse width \leqq 300us , duty cycle \leqq 2%

3.The EAS data shows Max. rating . The test condition is VDD=25V,VGS=10V,L=0.1mH,IAS=22.6A

4.The power dissipation is limited by 150°C junction temperature

5. The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.



AOD4130-HXY N-Channel Enhancement Mode MOSFET

Typical Characteristics

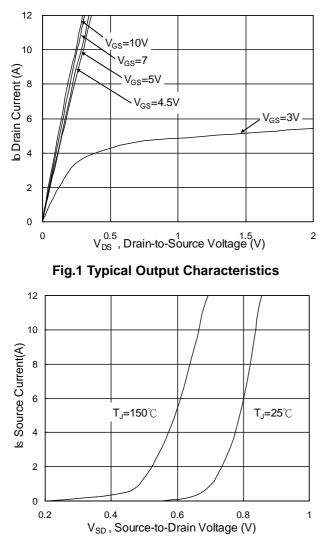


Fig.3 Forward Characteristics of Reverse

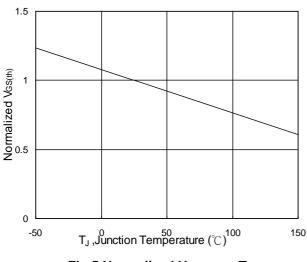


Fig.5 Normalized $V_{GS(th)}$ v.s T_J

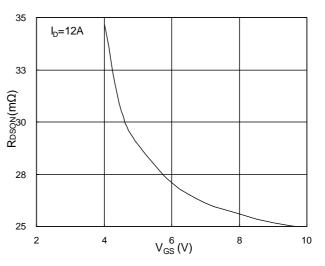


Fig.2 On-Resistance v.s Gate-Source

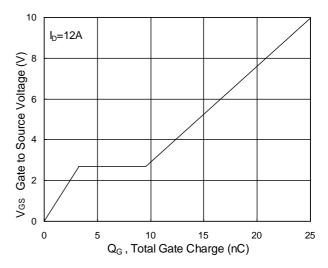


Fig.4 Gate-Charge Characteristics

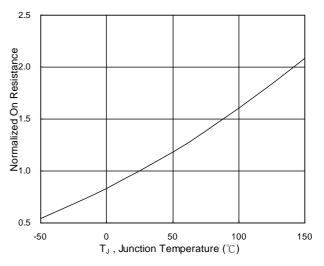


Fig.6 Normalized R_{DSON} v.s T_J



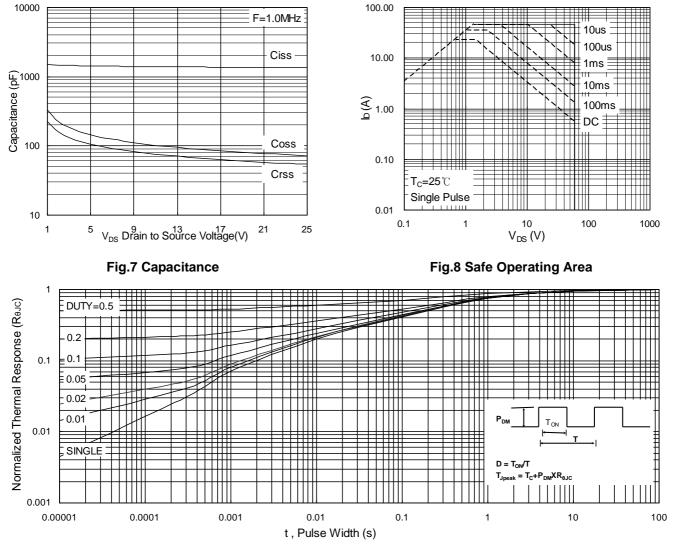


Fig.9 Normalized Maximum Transient Thermal Impedance

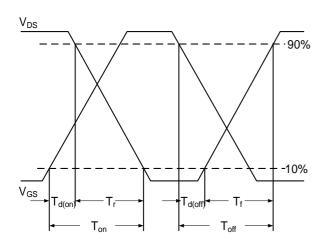
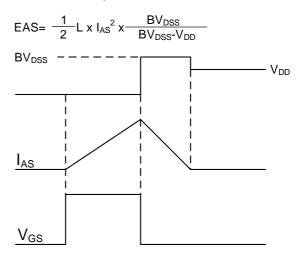
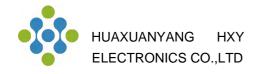


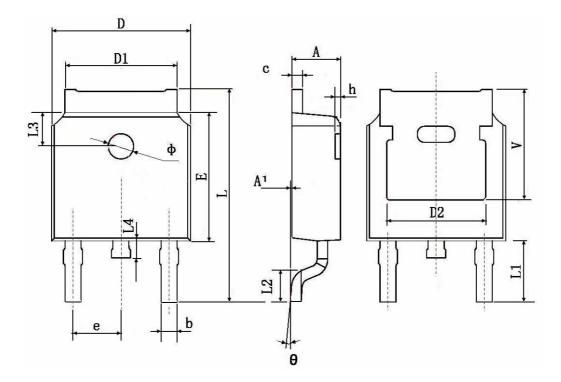
Fig.10 Switching Time Waveform







TO252-2L Package Information



	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
А	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
b	0.660	0.860	0.026	0.034	
С	0.460	0.580	0.018	0.023	
D	6.500	6.700	0.256	0.264	
D1	5.100	5.460	0.201	0.215	
D2	0.483	0.483 TYP.) TYP.	
E	6.000	6.200	0.236	0.244	
е	2.186	2.386	0.086	0.094	
L	9.800	10.400	0.386	0.409	
L1	2.900 TYP.		0.114	TYP.	
L2	1.400	1.700	0.055	0.067	
L3	1.600 TYP.		0.063	0.063 TYP.	
L4	0.600	1.000	0.024	0.039	
Φ	1.100	1.300	0.043	0.051	
θ	0°	8°	0 °	8°	
h	0.000	0.300	0.000	0.012	
V	5.350	TYP.	0.211 TYP.		



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